



Material Content Data Sheet



Sales Product Name		BFR 93AW H6327		Issued		19. January 2016			
MA#		MA000757502							
Package		PG-SOT323-3-1		Weight*		5.96 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.002	0.03		348		
	non noble metal	tin	7440-31-5	0.001	0.01		90		
	inorganic material	silicon	7440-21-3	0.015	0.26	0.30	2577	3015	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88		
	non noble metal	titanium	7440-32-6	0.003	0.04		441		
	non noble metal	chromium	7440-47-3	0.008	0.13		1323		
	non noble metal	copper	7440-50-8	2.617	43.93	44.11	439307	441159	
wire	noble metal	gold	7440-57-5	0.008	0.13	0.13	1307	1307	
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5303		
	plastics	epoxy resin	-	0.679	11.40		114011		
	inorganic material	silicondioxide	60676-86-0	2.448	41.10	53.03	410969	530283	
leadfinish	non noble metal	tin	7440-31-5	0.134	2.26	2.26	22555	22555	
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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